L Number	Hits	Search Text	DB	Time stamp
2	104098	(detach$3 remov$3) near10 (wafer substrate)	USPAT; US-PGPUB	2003/11/14 18:04
3	57609	((detach$3 remov$3) near10 (wafer substrate)) and (insulat$3 dielectric)	USPAT; US-PGPUB	2003/11/14 18:04
4	50728	(((detach$3 remov$3) near10 (wafer substrate)) and (insulat$3 dielectric)) and (etch$3 pattern$3)	USPAT; US-PGPUB	2003/11/14 18:05
5	47194	((((detach$3 remov$3) near10 (wafer substrate)) and (insulat$3 dielectric)) and (etch$3 pattern$3)) and (metal contact wire)	USPAT; US-PGPUB	2003/11/14 20:37
7	3843	(((((detach$3 remov$3) near10 (wafer substrate)) and (insulat$3 dielectric)) and (etch$3 pattern$3)) and (metal contact wire)) and Sacrificial	USPAT; US-PGPUB	2003/11/14 20:39
8	915	((((((detach$3 remov$3) near10 (wafer substrate)) and (insulat$3 dielectric)) and (etch$3 pattern$3)) and (metal contact wire)) and Sacrificial) and wire	USPAT; US-PGPUB	2003/11/14 21:18
9	153115	438/$.ccls. or 257/$.ccls.	USPAT; US-PGPUB	2003/11/14 21:20
10	40539	((detach$3 remov$3) near10 (wafer substrate)) and (438/$.ccls. or 257/$.ccls.)	USPAT; US-PGPUB	2003/11/14 21:20
11	28706	(((detach$3 remov$3) near10 (wafer substrate)) and (438/$.ccls. or 257/$.ccls.)) and (((((detach$3 remov$3) near10 (wafer substrate)) and (insulat$3 dielectric)) and (etch$3 pattern$3)) and (metal contact wire))	USPAT; US-PGPUB	2003/11/14 21:21
12	2654	((((detach$3 remov$3) near10 (wafer substrate)) and (438/$.ccls. or 257/$.ccls.)) and (((((detach$3 remov$3) near10 (wafer substrate)) and (insulat$3 dielectric)) and (etch$3 pattern$3)) and (metal contact wire))) and ((((((detach$3 remov$3) near10 (wafer substrate)) and (insulat$3 dielectric)) and (etch$3 pattern$3)) and (metal contact wire)) and Sacrificial)	USPAT; US-PGPUB	2003/11/14 21:23